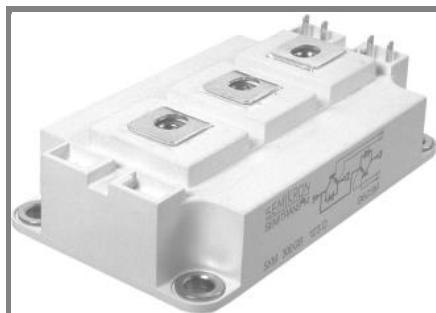




SEMITRANS® 3

Trench IGBT Modules

SKM 200GB176D

SKM 200GAL176D

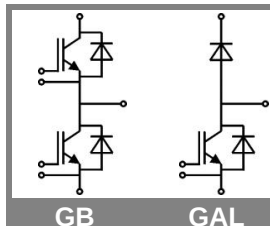
Preliminary Data

Features

- Homogeneous Si
- Trench = Trenchgate technology
- V_{CEsat} with positive temperature coefficient
- High short circuit capability, self limiting to $6 \times I_C$

Typical Applications

- AC inverter drives mains 575 - 750 V AC
- Public transport (auxiliary syst.)

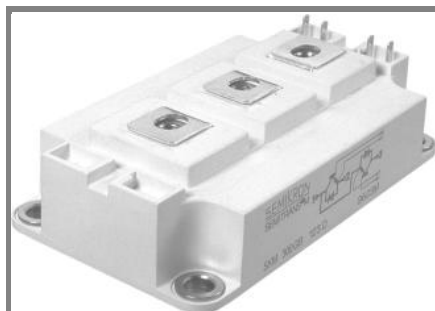


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Absolute Maximum Ratings				$T_c = 25^\circ\text{C}$, unless otherwise specified	
Symbol	Conditions			Values	Units
IGBT					
V_{CES}	$T_j = 25^\circ\text{C}$			1700	V
I_C	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$		260	A
		$T_c = 80^\circ\text{C}$		180	A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$, $t_p = 1\text{ ms}$			300	A
V_{GES}				± 20	V
t_{psc}	$V_{CC} = 1200\text{ V}$; $V_{GE} \leq 20\text{ V}$; $T_j = 125^\circ\text{C}$ $V_{CES} < 1700\text{ V}$			10	μs
Inverse Diode					
I_F	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$		210	A
		$T_c = 80^\circ\text{C}$		140	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$, $t_p = 1\text{ ms}$			300	A
I_{FSM}	$t_p = 10\text{ ms}$; sin.	$T_j = 150^\circ\text{C}$		1100	A
Freewheeling Diode					
I_F	$T_j = 150^\circ\text{C}$	$T_{case} = 25^\circ\text{C}$		210	A
		$T_{case} = 80^\circ\text{C}$		140	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$, $t_p = 1\text{ ms}$			300	A
I_{FSM}	$t_p = 10\text{ ms}$; sin.	$T_j = 150^\circ\text{C}$		1100	A
Module					
$I_{t(RMS)}$				500	A
T_{vj}				- 40 ... + 150	$^\circ\text{C}$
T_{stg}	$T_{OPERATION} \leq T_{stg}$			-40...+125	$^\circ\text{C}$
V_{isol}	AC, 1 min.			4000	V

Characteristics			T _c = 25 °C, unless otherwise specified			
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 6 mA		5,2	5,8	6,4	V
I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES}	T _j = 25 °C		0,1	0,3	mA
V _{CE0}		T _j = 25 °C		1	1,2	V
		T _j = 125 °C		0,9	1,1	V
r _{CE}	V _{GE} = 15 V	T _j = 25°C		6,7	8,3	mΩ
		T _j = 125°C		10	12	mΩ
V _{CE(sat)}	I _{Cnom} = 150 A, V _{GE} = 15 V	T _j = 25°C _{chiplev.}		2	2,45	V
		T _j = 125°C _{chiplev.}		2,4	2,9	V
C _{ies}	V _{CE} = 25, V _{GE} = 0 V	f = 1 MHz		11,4		nF
C _{oes}				0,55		nF
C _{res}				0,44		nF
Q _G	V _{GE} = -8V...+15V			1200		nC
t _{d(on)}	R _{Gon} = 5 Ω	V _{CC} = 1200V I _{Cnom} = 150A T _j = 125 °C V _{GE} = ± 15V		360		ns
t _r				45		ns
E _{on}			93		mJ	
t _{d(off)}	R _{Goff} = 5 Ω			760		ns
t _f				140		ns
E _{off}			58		mJ	
R _{th(j-c)}	per IGBT				0,12	K/W



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SKM 200GAL176D

Preliminary Data

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- High short circuit capability, self limiting to $6 \times I_C$

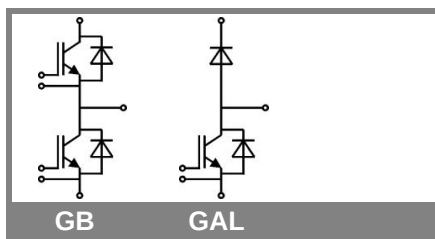
Typical Applications

- AC inverter drives mains 575 - 750 V AC
- Public transport (auxiliary syst.)

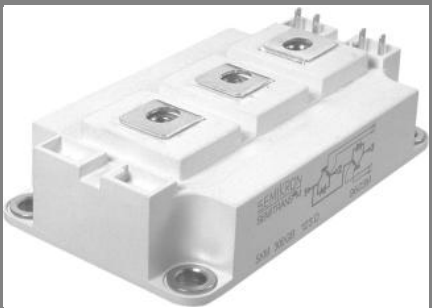
Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
Inverse Diode					
$V_F = V_{EC}$	$I_{Fnom} = 150 \text{ A}; V_{GE} = 0 \text{ V}$				
	$T_j = 25 \text{ }^\circ\text{C}_{chiplev.}$		1,7	1,9	V
	$T_j = 125 \text{ }^\circ\text{C}_{chiplev.}$		1,7	1,9	V
V_{F0}					
	$T_j = 25 \text{ }^\circ\text{C}$		1,1	1,3	V
	$T_j = 125 \text{ }^\circ\text{C}$		0,9	1,1	V
r_F					
	$T_j = 25 \text{ }^\circ\text{C}$		4	4	mΩ
	$T_j = 125 \text{ }^\circ\text{C}$		5,3	5,3	mΩ
I_{RRM}	$I_{Fnom} = 150 \text{ A}$		195		A
Q_{rr}	$di/dt = 3700 \text{ A}/\mu\text{s}$		52		μC
E_{off}	$V_{GE} = -15 \text{ V}; V_{CC} = 1200 \text{ V}$		31		mJ
$R_{th(j-c)D}$	per diode			0,25	K/W
FWD					
$V_F = V_{EC}$	$I_{Fnom} = 150 \text{ A}; V_{GE} = 0 \text{ V}$				
	$T_j = 25 \text{ }^\circ\text{C}_{chiplev.}$		1,7	1,9	V
	$T_j = 125 \text{ }^\circ\text{C}_{chiplev.}$		1,7	1,9	V
V_{F0}					
	$T_j = 25 \text{ }^\circ\text{C}$		1,1	1,3	V
	$T_j = 125 \text{ }^\circ\text{C}$		0,9	1,1	V
r_F					
	$T_j = 25 \text{ }^\circ\text{C}$		4	4	V
	$T_j = 125 \text{ }^\circ\text{C}$		5,3	5,3	V
I_{RRM}	$I_{Fnom} = 150 \text{ A}$		195		A
Q_{rr}	$di/dt = 3700 \text{ A}/\mu\text{s}$		52		μC
E_{off}	$V_{GE} = -15 \text{ V}; V_{CC} = 1200 \text{ V}$		31		mJ
$R_{th(j-c)FD}$	per diode			0,25	K/W
Module					
L_{CE}			15	20	nH
$R_{CC'+EE'}$	res., terminal-chip		0,35		mΩ
	$T_{case} = 25 \text{ }^\circ\text{C}$				
	$T_{case} = 125 \text{ }^\circ\text{C}$		0,5		mΩ
$R_{th(c-s)}$	per module			0,038	K/W
M_s	to heat sink M6	3		5	Nm
M_t	to terminals M6	2,5		5	Nm
w				325	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.



SKM 200GB176D...



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Trench IGBT Modules

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SKM 200GAL176D

Preliminary Data

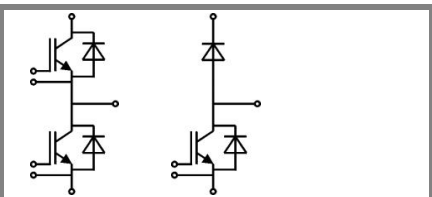
Features

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Typical Applications

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Z_{th} Symbol	Conditions	Values	Units
$Z_{th(j-c)I}$			
R_i	$i = 1$	80	mk/W
R_i	$i = 2$	30	mk/W
R_i	$i = 3$	8,2	mk/W
R_i	$i = 4$	1,8	mk/W
τ_{u_i}	$i = 1$	0,0753	s
τ_{u_i}	$i = 2$	0,01	s
τ_{u_i}	$i = 3$	0,0008	s
τ_{u_i}	$i = 4$	0,0003	s
$Z_{th(j-c)D}$			
R_i	$i = 1$	160	mk/W
R_i	$i = 2$	67	mk/W
R_i	$i = 3$	20	mk/W
R_i	$i = 4$	3	mk/W
τ_{u_i}	$i = 1$	0,0382	s
τ_{u_i}	$i = 2$	0,009	s
τ_{u_i}	$i = 3$	0,0009	s
τ_{u_i}	$i = 4$	0,005	s



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